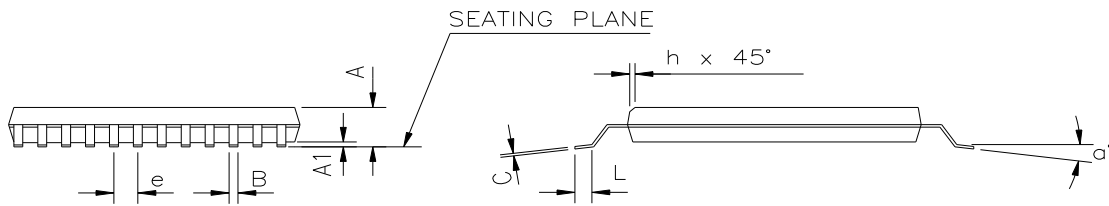
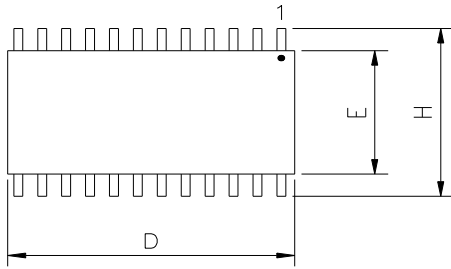


NOTES

1. LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF SOLDER PLATE
2. PACKAGE OUTLINE EXCLUSIVE OF MOLD FLASHES AND BURR DIMENSIONS
3. ALLOWABLE MOLD FLASH IS 5 MILS PER SIDE.
4. DIMENSIONS ARE GIVEN IN INCHES.
5. LEAD COPLANARITY IS 0.003 INCH MAX.



JEDEC #	MO-154BC	
TYPE	80 LEAD	
SYMBOL	Min	Max
A	0.059	0.069
A1	0.004	0.008
B	0.0067	0.009
C	0.005	0.008
D	0.803	0.811
E	0.150	0.157
e	0.0197 BSC	
H	0.228	0.244
h	0.010	0.016
L	0.020	0.030
α	0°	8°

PREPARED BY	NK	REF. NO. DIM-80Q3-01	REV. NO.	SPEL SEMICONDUCTOR LIMITED INDIA
CHECKED BY	SP		1	
APPROVED BY	NJC		DATE 01.07.01	

